

SUBSTRATE POLISHING APPARATUS AND
SUBSTRATE POLISHING METHOD

ABSTRACT OF THE DISCLOSURE

5 A substrate polishing apparatus wherein semiconductor
substrate is held by a top ring 10-2 or 11-2 and is pressed
against a polishing surface of a polishing table 10-1 or
10-2. A surface to be polished of the semiconductor
substrate is polished by a relative movement between the
semiconductor substrate and the polishing surface. The
10 apparatus includes pressing force changing mechanism for
changing an pressing force for pressing the semiconductor
substrate, relative movement seed changing mechanism for
changing the number of revolutions of the top ring and/or
the polishing table, and control mechanism. The control
15 mechanism performs the polishing through plural polishing
processes on the polishing table 10-1 or 10-2 while
changing the pressing force and the number of revolutions.